

EAST [10611340.wsp:1]

File View Edit Tools Window Help

S139: (188) S138 and S137
 S140: (67444) electrical\$3 near3 via
 S141: (60) S139 and S140
 S142: (529) electrical\$3 near3 trace near3 pattern\$3
 S143: (6) S141 and S142
 S144: (54) S141 not S143
 S145: (42) (compensat\$3 near network) with (impedance
 S146: (0) S144 and S145
 S147: (0) S144 and compensation and network
 S148: (2) S144 and (impedance near match\$3)
 S149: (597) (substrate PCB (printed adj circuit adj board
 S150: (170) S149 and S138
 S152: (6) S151 and S142
 S151: (49) S150 and S140
 S153: (85) (substrate PCB (printed adj circuit adj board
 S154: (28) S140 and S153

avorites

Default operator: OR

US:PGPUB:USPAT:EPO:JPO:DERWENT:IBM:IDB

Plurals

Highlight all hit terms initially

(substrate PCB (printed adj circuit adj board) (laminare near5 base near3 plate))
 with (thick\$4 near5 (mil mm milimeter micron)) and ball near grid and lid

BRS form ISAR form Image Text HTML

	U	I	Document ID	Issue Date	Pages	Title	Current	Cur	Re	Inventor	S	C	P	3	
1	r	r	US 20040217770 A1	20041104	9	Planarizing and testing o	324/754			DiOrio, Mark L.	r	r	r	r	r
2	r	r	US 20040164424 A1	20040826	16	Flexibility enhanced inte	257/776	257/		Silverbrook, Kia	r	r	r	r	r
3	r	r	US 20040155337 A1	20040812	19	High density chip level p	257/738			Strandberg, Jan I. et	r	r	r	r	r
4	r	r	US 20040150118 A1	20040805	33	Warp-suppressed semico	257/778	257/		Honda, Hirokazu	r	r	r	r	r
5	r	r	US 20040099958 A1	20040527	14	Crack resistant interconn	257/778	257/		Schildgen, William	r	r	r	r	r
6	r	r	US 20040099943 A1	20040527	42	Substrate sheet material f	257/701	257/		Meguro, Kouichi et	r	r	r	r	r
7	r	r	US 20040084764 A1	20040506	23	Package structure, printe	257/706			Ishimine, Junichi et	r	r	r	r	r
8	r	r	US 20040080917 A1	20040429	18	Integrated microwave pac	361/748			Steddom, Clark Mo	r	r	r	r	r
9	r	r	US 20040037059 A1	20040226	19	Integrated circuit packag	361/764	257/		Stiborek, Leon et al	r	r	r	r	r

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